



# BUK6Y32-60P

60 V, P-channel Trench MOSFET

5 July 2018

Product data sheet

## 1. General description

P-channel enhancement mode MOSFET in an LFPAK56 (Power SO8) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

This product has been designed and qualified to AEC-Q101 standard for use in high-performance automotive applications such as reverse battery protection.

## 2. Features and benefits

- High thermal power dissipation capability
- Suitable for thermally demanding environments due to 175 °C rating
- Trench MOSFET technology
- AEC-Q101 qualified

## 3. Applications

- Reverse battery protection
- Power management
- High-side loadswitch
- Motor drive

## 4. Quick reference data

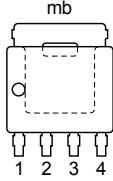
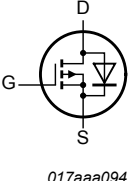
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$	-	-	-60	V
$V_{GS}$	gate-source voltage	[1]	-20	-	20	V
$I_D$	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ °C}$	-	-	-40	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$	-	-	106	W
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -10\text{ V}; I_D = -6.6\text{ A}; T_j = 25\text{ °C}$	-	25	32	mΩ

[1]  $V_{GS} = -20\text{ V}/+5\text{ V}$  according AEC-Q101 at  $T_j = 175\text{ °C}$ ;  $V_{GS} = -20\text{ V}/+20\text{ V}$  according AEC-Q101 at  $T_j = 150\text{ °C}$

## 5. Pinning information

**Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p><b>LFPAK56; Power-SO8 (SOT669)</b></p>	 <p>017aaa094</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

## 6. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BUK6Y32-60P	LFPAK56; Power-SO8	plastic, single-ended surface-mounted package; 4 terminals	SOT669

## 7. Marking

**Table 4. Marking codes**

Type number	Marking code
BUK6Y32-60P	6Y3260P

## 8. Limiting values

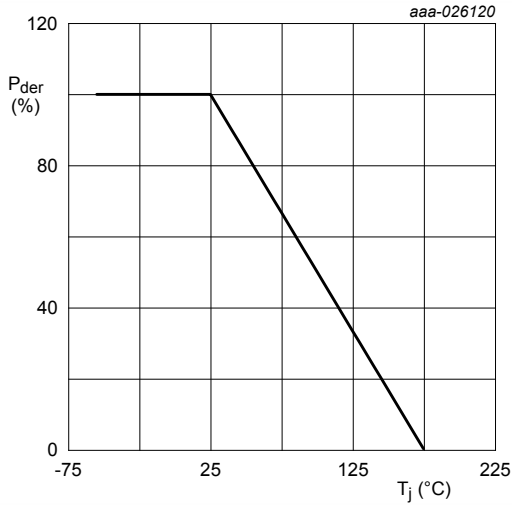
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25\text{ °C}$		-	-60	V
$V_{GS}$	gate-source voltage		[1]	-20	20	V
$I_D$	drain current	$V_{GS} = -10\text{ V}; T_{mb} = 25\text{ °C}$		-	-40	A
		$V_{GS} = -10\text{ V}; T_{mb} = 100\text{ °C}$		-	-28	A
$I_{DM}$	peak drain current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ °C}$		-	-158	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$		-	106	W
$T_j$	junction temperature			-55	175	°C
$T_{amb}$	ambient temperature			-55	175	°C
$T_{stg}$	storage temperature			-65	175	°C
<b>Source-drain diode</b>						
$I_S$	source current	$T_{mb} = 25\text{ °C}$		-	-40	A
$I_{SM}$	peak source current	single pulse; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ °C}$		-	-158	A
<b>ESD maximum rating</b>						
$V_{ESD}$	electrostatic discharge voltage	HBM	[2]	-	1000	V
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{sup} \leq -60\text{ V}; V_{GS} = -10\text{ V}; T_{j(init)} = 25\text{ °C}; I_D = -8.2\text{ A}; \text{DUT in avalanche (unclamped)}$		-	6.6	mJ

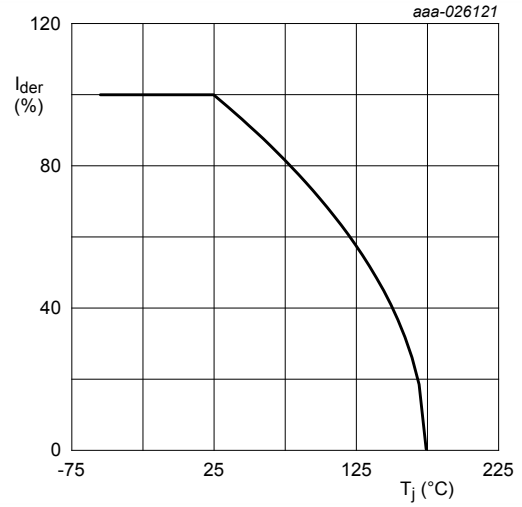
[1]  $V_{GS} = -20\text{ V}/+5\text{ V}$  according AEC-Q101 at  $T_j = 175\text{ °C}$ ;  $V_{GS} = -20\text{ V}/+20\text{ V}$  according AEC-Q101 at  $T_j = 150\text{ °C}$

[2] Measured between all pins.



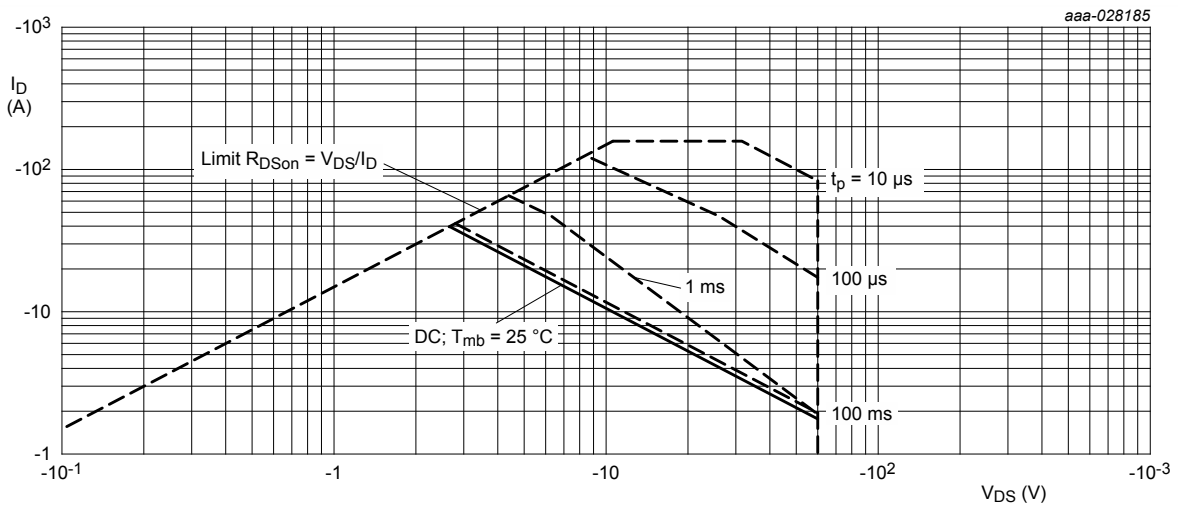
$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100 \%$$

**Fig. 1. Normalized total power dissipation as a function of junction temperature**



$$I_{der} = \frac{I_D}{I_{D(25^\circ\text{C})}} \times 100 \%$$

**Fig. 2. Normalized continuous drain current as a function of junction temperature**

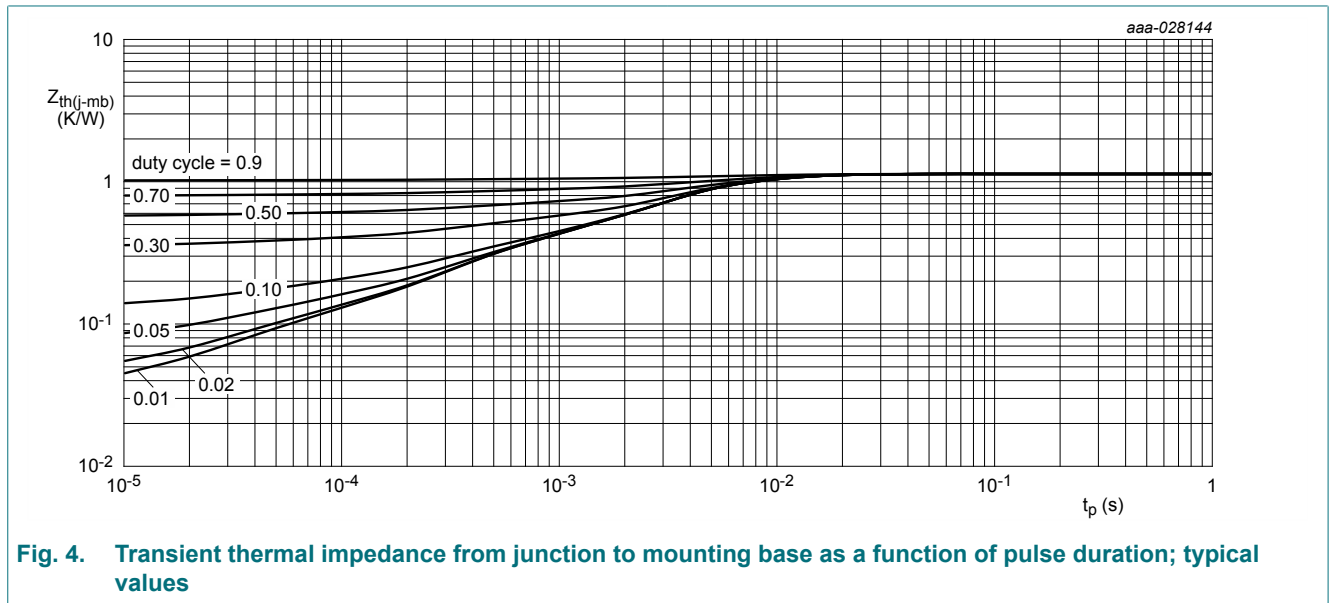


**Fig. 3. Safe operating area; junction to mounting base; continuous and peak drain currents as a function of drain-source voltage**

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	1.1	1.4	K/W



**Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration; typical values**

## 10. Characteristics

**Table 7. Characteristics**
*T<sub>j</sub> = 25 °C unless otherwise specified*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V	-60	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	I <sub>D</sub> = -250 μA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 25 °C	-1.5	-2	-3	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = -60 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-1	μA
		V <sub>DS</sub> = -60 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	-	-50	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
		V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-100	nA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -6.6 A; T <sub>j</sub> = 25 °C	-	25	32	mΩ
		V <sub>GS</sub> = -10 V; I <sub>D</sub> = -6.6 A; T <sub>j</sub> = 175 °C	-	53	67	mΩ
		V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -6.4 A	-	29	34	mΩ
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -2 A; T <sub>j</sub> = 25 °C	-	47	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz	-	6.1	-	Ω
<b>Dynamic characteristics</b>						
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = -30 V; I <sub>D</sub> = -6.6 A; V <sub>GS</sub> = -10 V	-	46	52.9	nC
Q <sub>GS</sub>	gate-source charge		-	7.3	-	nC
Q <sub>GD</sub>	gate-drain charge		-	9.4	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -30 V; f = 1 MHz; V <sub>GS</sub> = 0 V	-	2590	-	pF
C <sub>oss</sub>	output capacitance		-	202	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	118	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = -30 V; I <sub>D</sub> = -6.6 A; V <sub>GS</sub> = -10 V; R <sub>G(ext)</sub> = 6 Ω	-	9	-	ns
t <sub>r</sub>	rise time		-	16	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	81	-	ns
t <sub>f</sub>	fall time		-	31	-	ns
<b>Source-drain diode</b>						
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -39.5 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-0.7	-1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = -6.6 A; dI <sub>S</sub> /dt = 100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = -30 V; T <sub>j</sub> = 25 °C	-	28	-	ns
Q <sub>r</sub>	recovered charge		-	29	-	nC

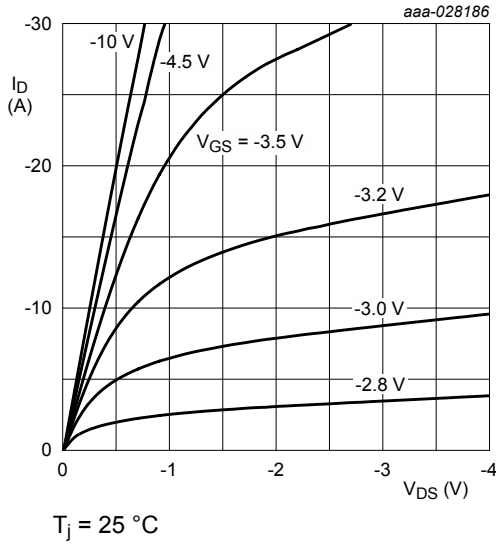


Fig. 5. Output characteristics: drain current as a function of drain-source voltage; typical values

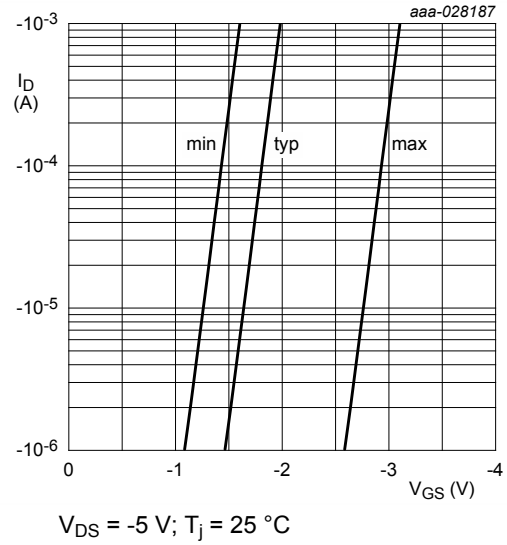


Fig. 6. Sub-threshold drain current as a function of gate-source voltage

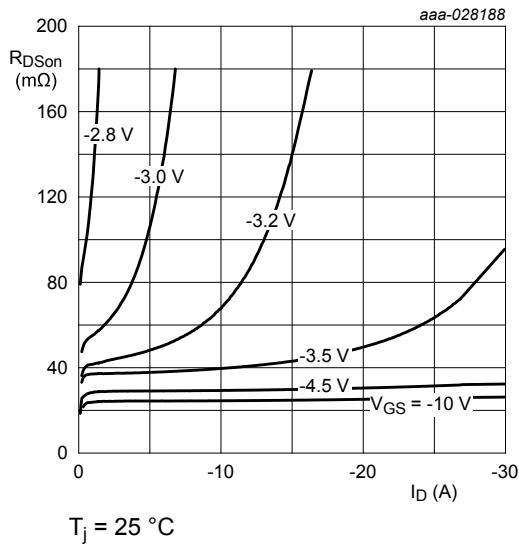


Fig. 7. Drain-source on-state resistance as a function of drain current; typical values

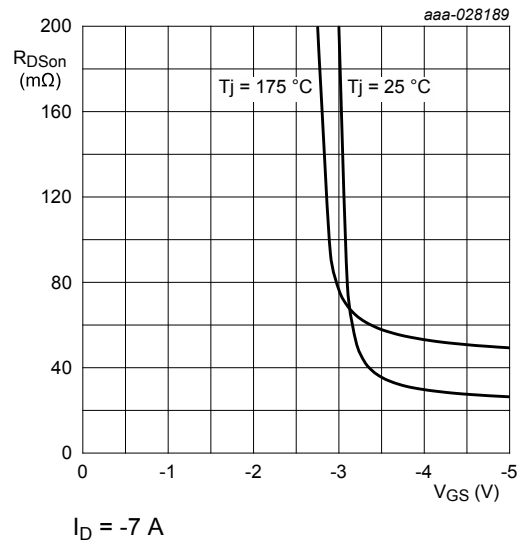
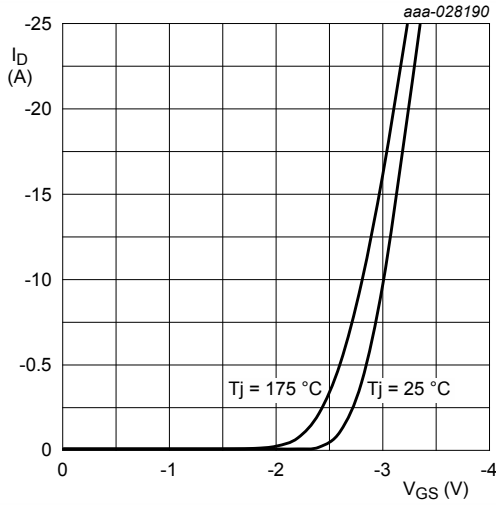
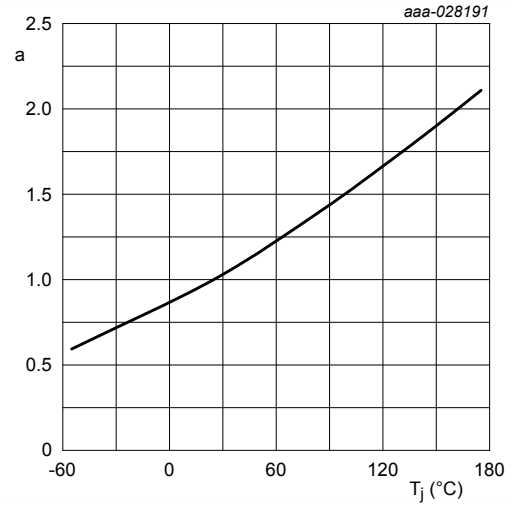


Fig. 8. Drain-source on-state resistance as a function of gate-source voltage; typical values



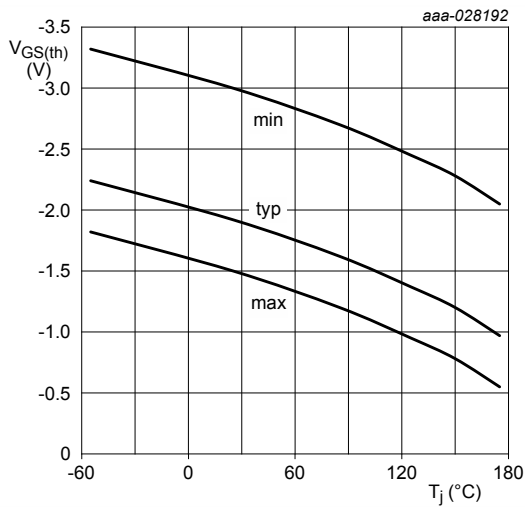
$$V_{DS} > I_D \times R_{DSon}$$

**Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



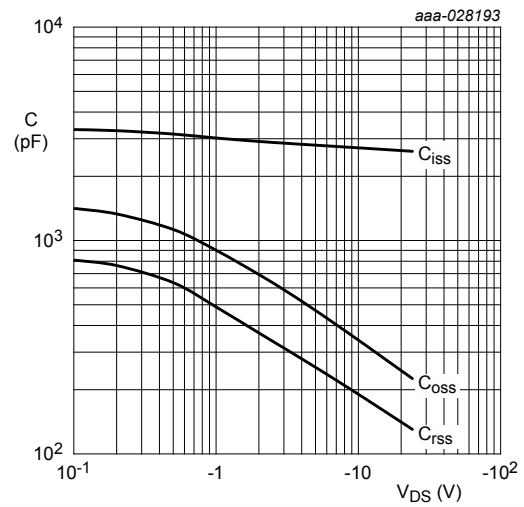
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ C)}}$$

**Fig. 10. Normalized drain-source on-state resistance as a function of junction temperature; typical values**



$$I_D = -250 \mu A; V_{DS} = V_{GS}$$

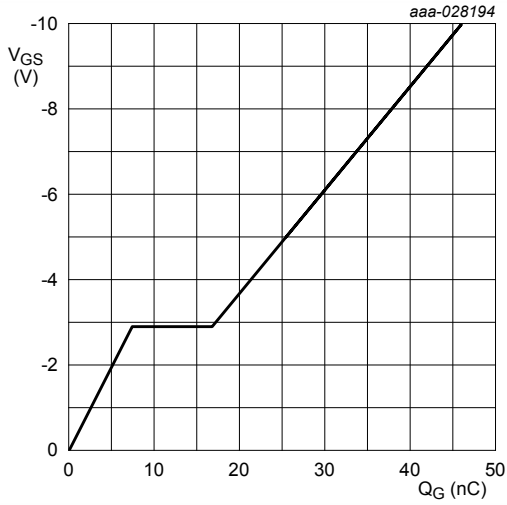
**Fig. 11. Gate-source threshold voltage as a function of junction temperature**



$$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$$

**Fig. 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**





$V_{DS} = -30\text{ V}$ ;  $I_D = -8.2\text{ A}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$

Fig. 13. Gate-source voltage as a function of gate charge; typical values

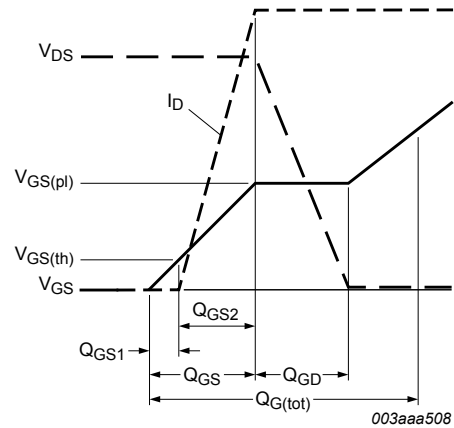
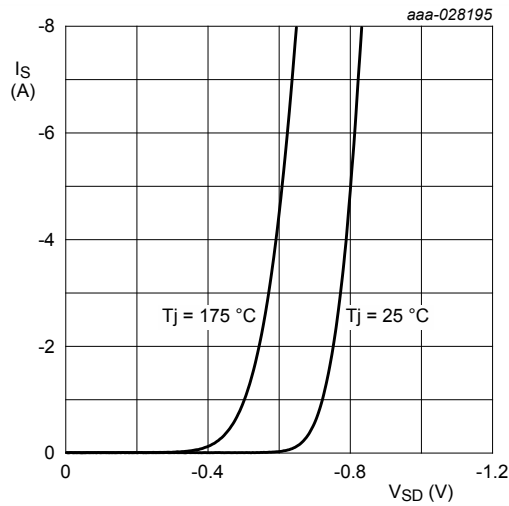


Fig. 14. Gate charge waveform definitions



$V_{GS} = 0\text{ V}$

Fig. 15. Source current as a function of source-drain voltage; typical values

## 11. Test information

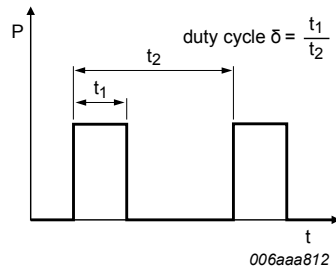


Fig. 16. Duty cycle definition

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline

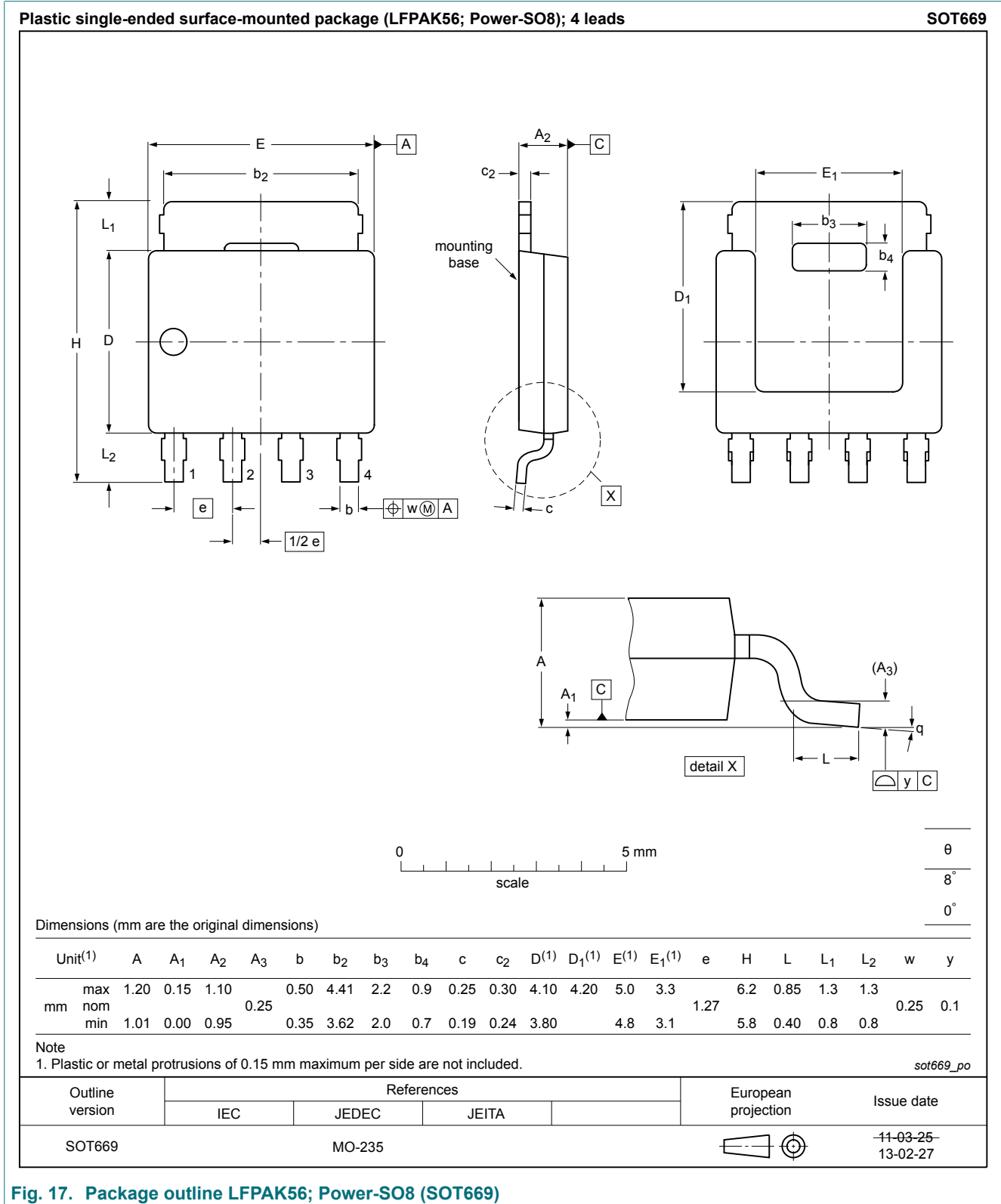


Fig. 17. Package outline LFAK56; Power-SO8 (SOT669)

### 13. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BUK6Y32-60P v.3	20180705	Product data sheet	-	BUK6Y32-60P v.2
Modifications:	<ul style="list-style-type: none"><li>Characteristics: Fig. 5 updated.</li></ul>			
BUK6Y32-60P v.2	20180607	Product data sheet	-	BUK6Y32-60P v.1
BUK6Y32-60P v.1	20180309	Product data sheet	-	-

## 14. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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